

Terminal Pad Solderability:
 Meets EIA Specification RS186-9E
 And ANSI/J-STD-002 Category 3.

Terminal Pad Materials:
 Tin-plated Nickel-Copper

Lead-Free, RoHS Compliant

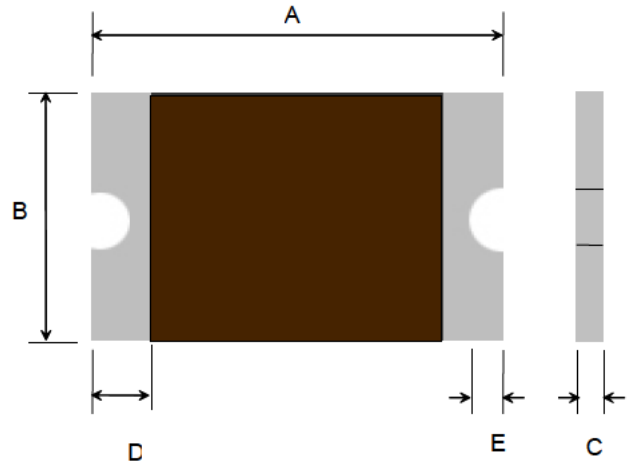


TABLE I. DIMENSIONS:

Model	Marking	A		B		C		D
		Min.	Max.	Min.	Max.	Min.	Max.	Min.
BpS03-200-09	2	1.45	1.85	0.65	1.05	0.40	1.00	0.15

Unit:mm

TABLE II. PERFORMANCE RATING:

Model	Marking	V_{max} (Vdc)	I_{max} (A)	I_{hold} @25°C (A)	I_{trip} @25°C (A)	P_d Typ. (W)	Maximum Time To Trip		Resistance	
							Current (A)	Time (Sec)	$R_{i_{min}}$ (Ω)	$R_{1_{max}}$ (Ω)
BpS03-200-09	2	9.0	40	0.20	0.50	0.50	1.0	0.60	0.550	3.500

I_{hold} = Hold Current. Maximum current device will not trip in 25°C still air.

I_{trip} = Trip Current. Minimum current at which the device will always trip in 25°C still air.

V_{max} = Maximum operating voltage device can withstand without damage at rated current (I_{max}).

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).

P_d = Maximum power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

$R_{i_{min}}/_{max}$ = Minimum/Maximum device resistance prior to tripping at 25°C.

$R_{1_{max}}$ = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.